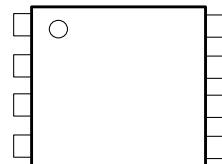
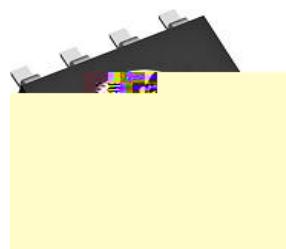


80V N-Ch Power MOSFET

V_{DS}	80	V
$R_{DS(on),typ}$	$V_{GS}=10V$	4.8
$R_{DS(on),typ}$	$V_{GS}=4.5V$	6.2
I_D	16.6	A



Part Number	Package	Marking
HGS063N08SL	SOIC-8	GS063N08SL

Absolute Maximum Ratings at T_J

Parameter	Symbol	Conditions	Value	Unit
Continuous Drain Current (Silicon Limited)	I_D	T_C	17	A
		T_C	10	
Drain to Source Voltage	V_{DS}	-	80	V
Gate to Source Voltage	V_{GS}	-	20	V
Pulsed Drain Current	I_{DM}	-	120	A
Avalanche Energy, Single Pulse	E_{AS}	$L=0.3mH, T_C$	240	mJ
Power Dissipation	P_D	T_C	3.1	W
Operating and Storage Temperature	T_J, T_{stg}	-	-55 to 150	

Absolute Maximum Ratings

Parameter	Symbol	Max	Unit	
Thermal Resistance Junction-Lead	R_{JL}	23		
Thermal Resistance Junction-Ambient (steady state)		40		
		75		

Electrical Characteristics at T_J
Static Characteristics

Parameter	Symbol	Conditions	Value			Unit
			min	typ	max	
Drain to Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS}=0V, I_D=250A$	80	-	-	V
Gate Threshold Voltage	$V_{GS(th)}$	$V_{GS}=V_{DS}, I_D=250A$	1.0	1.7	2.4	
Zero Gate Voltage Drain Current	I_{DSS}	$V_{GS}=0V, V_{DS}=80V, T_J$	-	-	1	A
		$V_{GS}=0V, V_{DS}=80V, T_J$	-	-	100	
Gate to Source Leakage Current	I_{GSS}	$V_{GS} \leq 99, V_{DS}=0V$	-	-	100	nA
Drain to Source on Resistance	$R_{DS(on)}$	$V_{GS}=10V, I_D=14A$	-	4.8	6.3	m
		$V_{GS}=4.5V, I_D=10A$	-	6.2	8.5	
Transconductance	g_{fs}	$V_{DS}=5V, I_D=14A$	-	50	-	S
Gate Resistance	R_G	$V_{GS}=0V, V_{DS} \text{ Open}, f=1MHz$	-	1.5	-	

Dynamic Characteristics

Input Capacitance	C_{iss}	$V_{GS}=0V, V_{DS}=40V, f=1MHz$	-	3130	-	pF
Output Capacitance	C_{oss}		-	385	-	
Reverse Transfer Capacitance	C_{rss}		-	18	-	
Total Gate Charge	$Q_g(10V)$	$V_{DD}=40V, I_D=14A, V_{GS}=10V$	-	46	-	nC
Total Gate Charge	$Q_g(4.5V)$		-	22	-	
Gate to Source Charge	Q_{gs}		-	9	-	
Gate to Drain (Miller) Charge	Q_{gd}		-	8	-	
Turn on Delay Time	$t_{d(on)}$	$V_{DD}=40V, I_D=14A, V_{GS}=10V, R_G=10\Omega$	-	11	-	ns
Rise time	t_r		-	7	-	
Turn off Delay Time	$t_{d(off)}$		-	38	-	
Fall Time	t_f		-	9	-	

Reverse Diode Characteristics

Diode Forward Voltage	V_{SD}	$V_{GS}=0V, I_F=14A$	-	0.9	1.2	V
Reverse Recovery Time	t_{rr}	$V_R=40V, I_F=14A, dI_F/dt=500A/s$	-	48	-	ns
Reverse Recovery Charge	Q_{rr}		-	190	-	nC

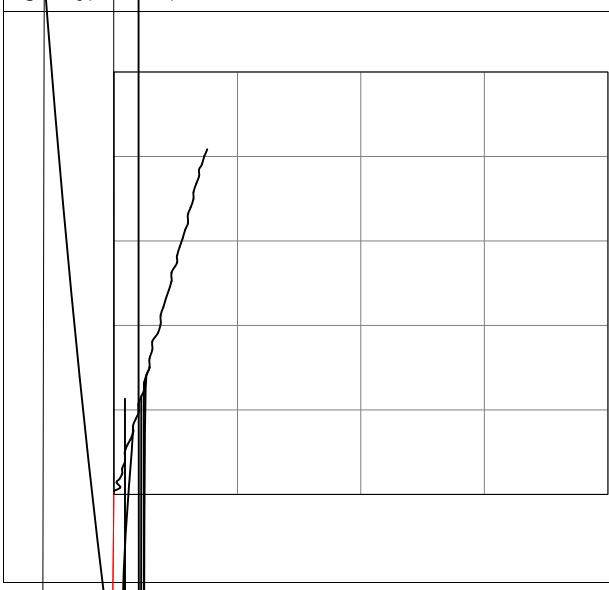
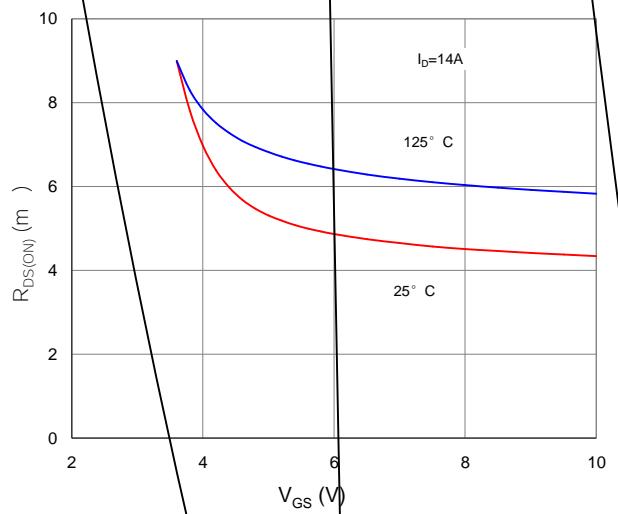
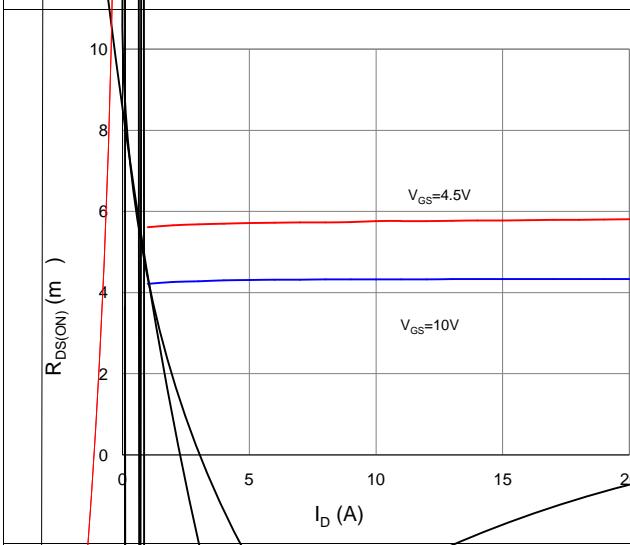
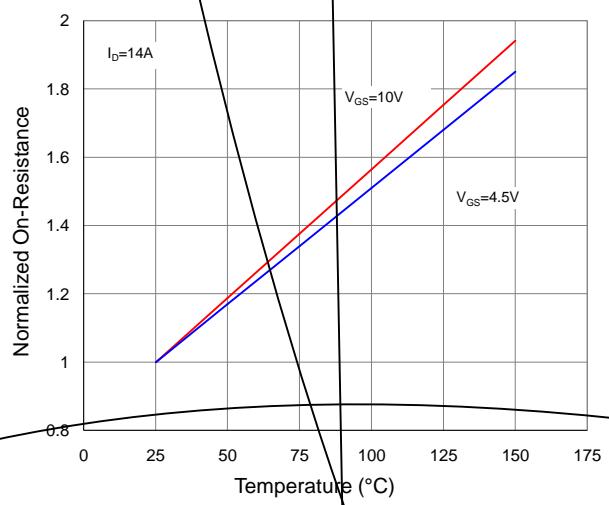
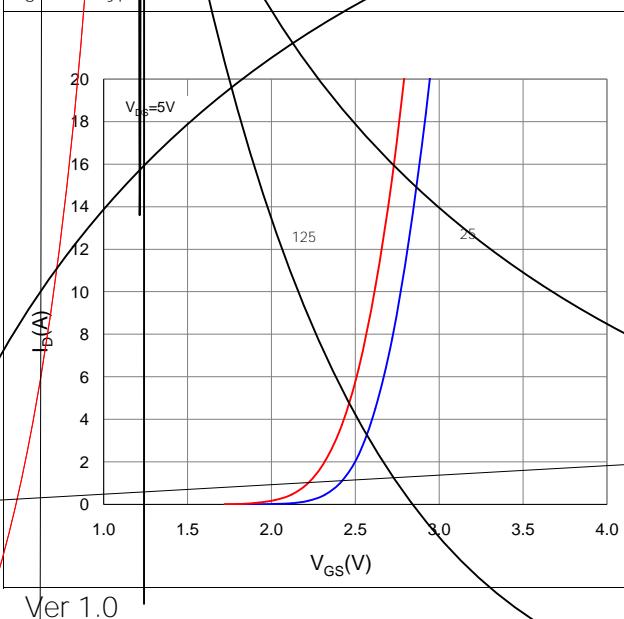
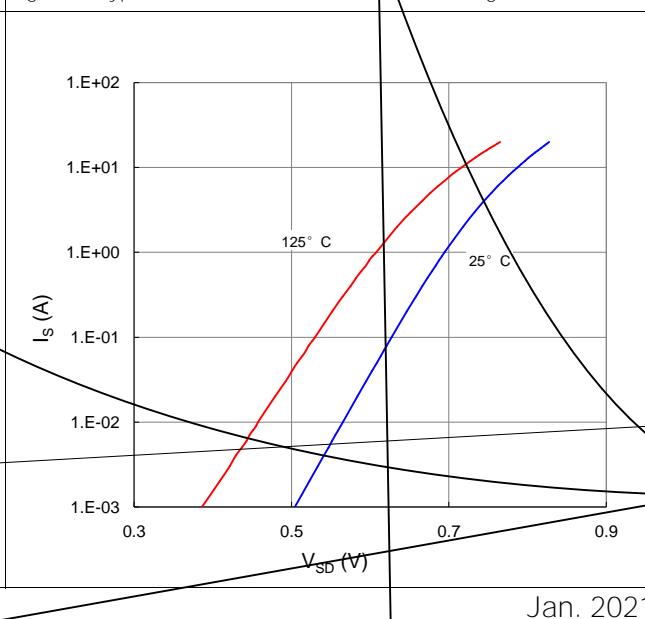
Fig 1. Typical Output Characteristics

Figure 2. On-Resistance vs. Gate-Source Voltage

Figure 3. On-Resistance vs. Drain Current and Gate Voltage

Figure 4. Normalized On-Resistance vs. Junction Temperature

Figure 5. Typical Transfer Characteristics

Figure 6. Typical Source-Drain Diode Forward Voltage


Figure 7. Typical Gate-Charge vs. Gate-to-Source Voltage

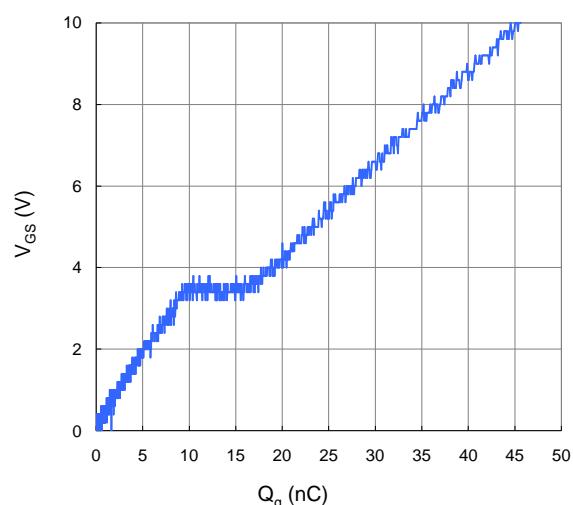


Figure 8. Typical Capacitance vs. Drain-to-Source Voltage



Figure 9. Maximum Safe Operating Area

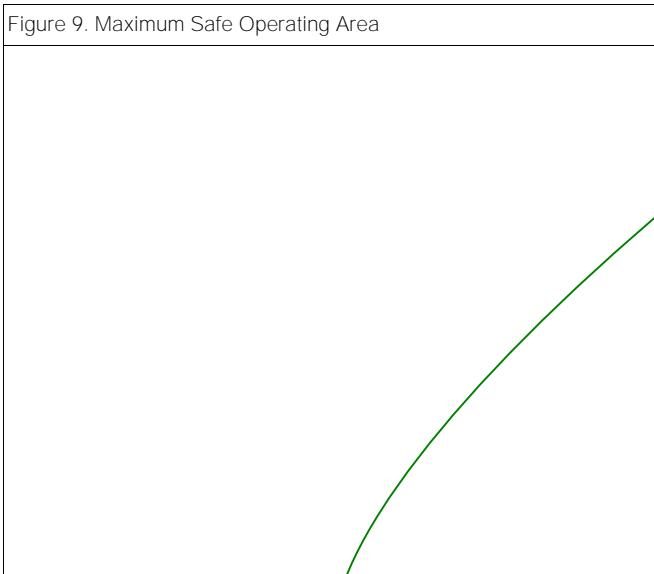


Figure 10. Maximum Drain Current vs. Case Temperature

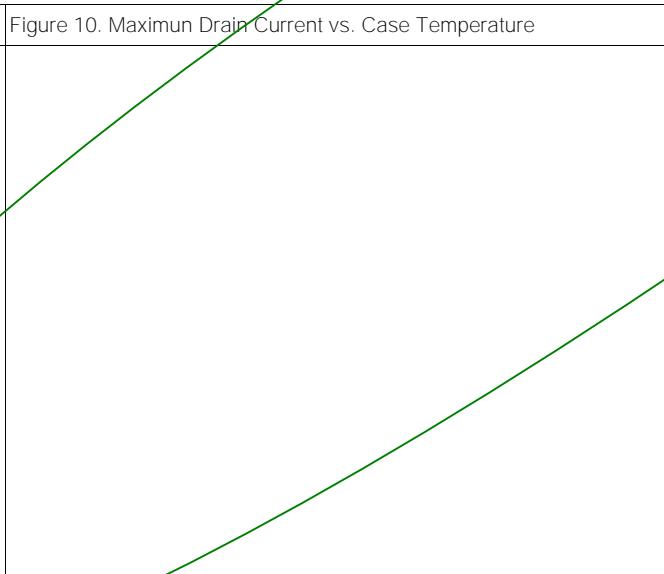
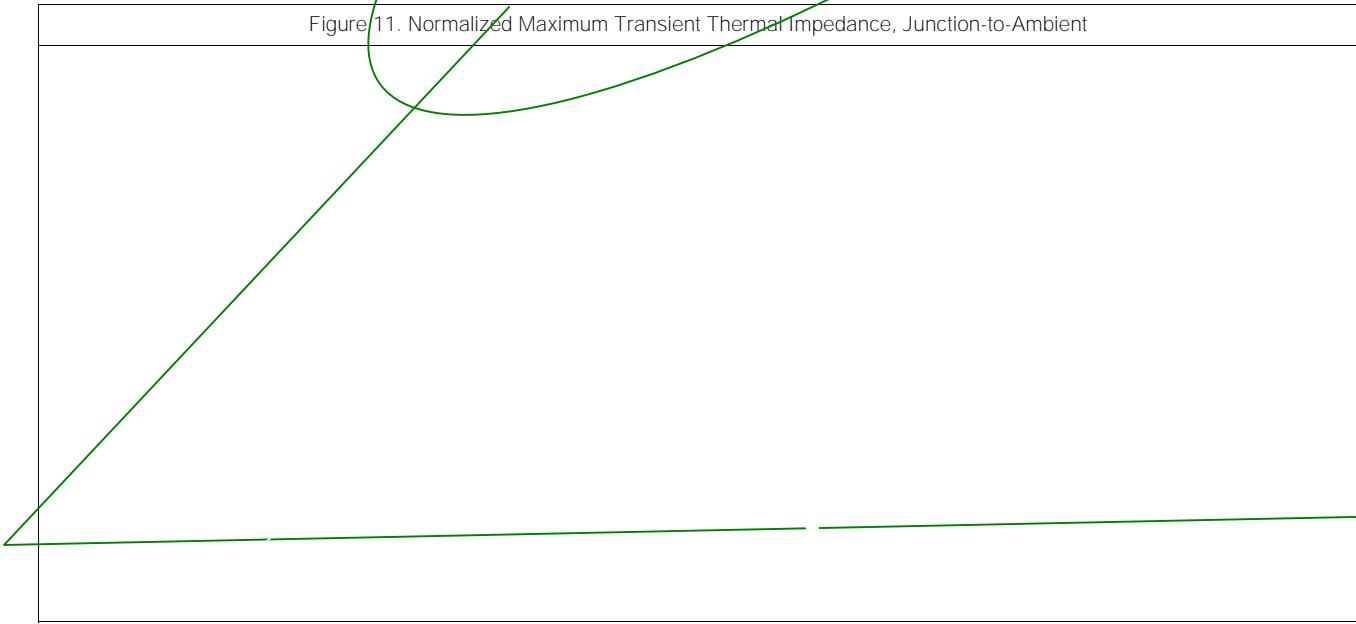
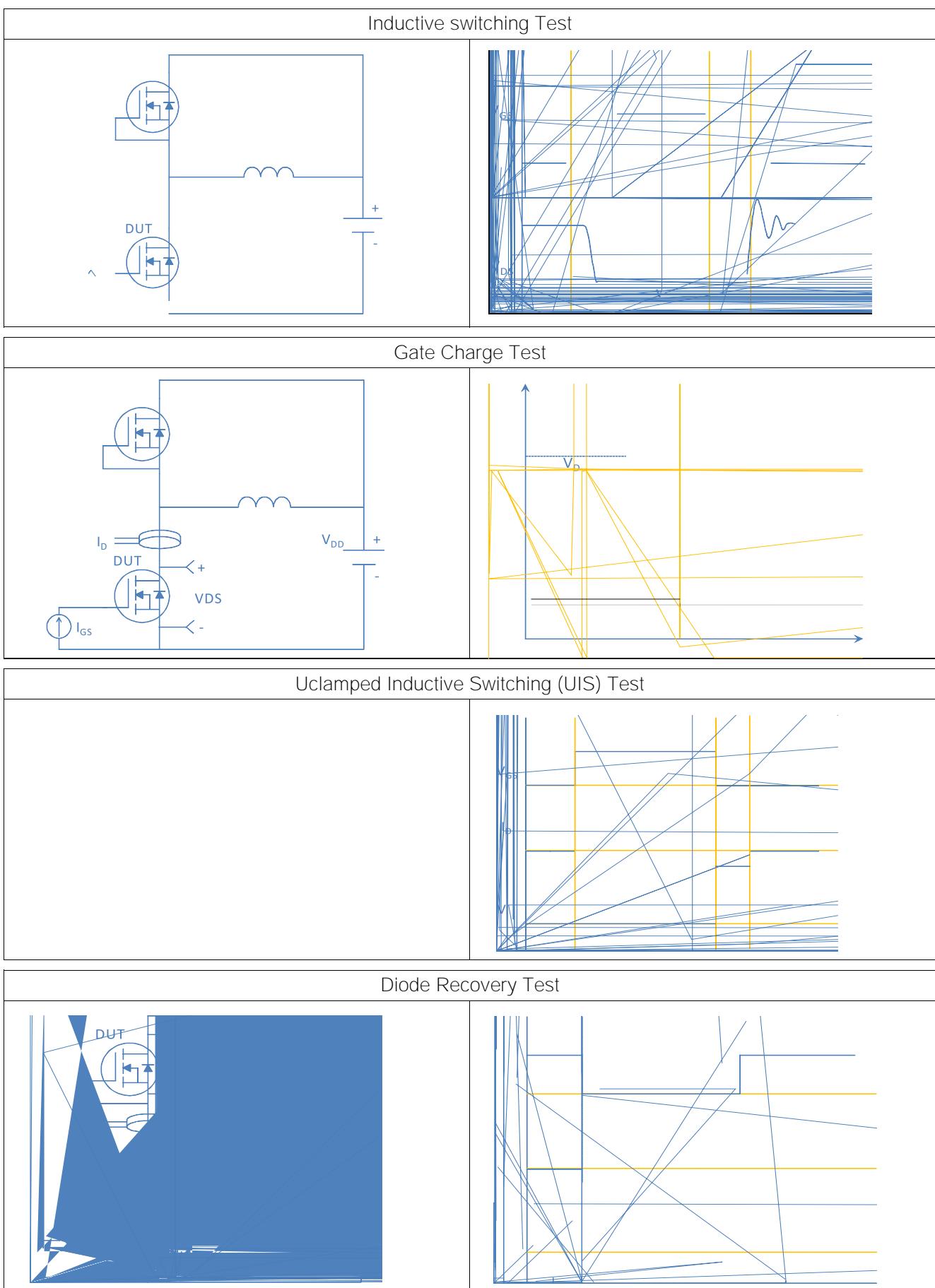


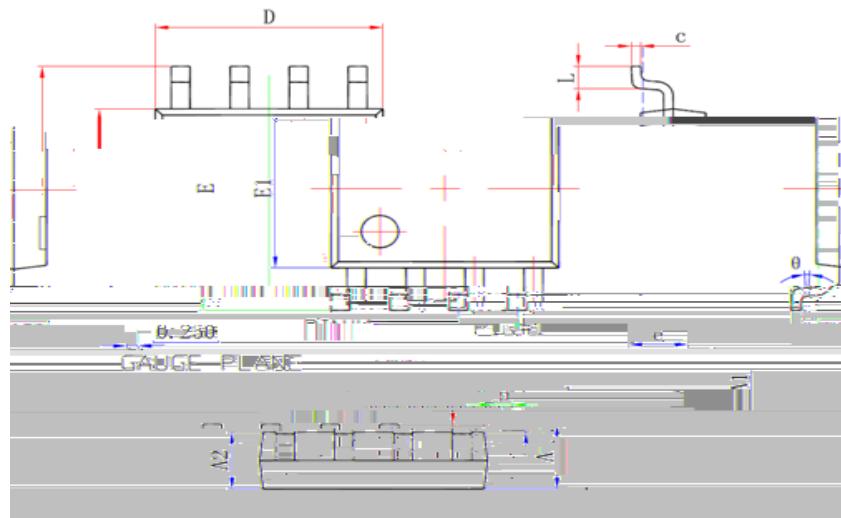
Figure 11. Normalized Maximum Transient Thermal Impedance, Junction-to-Ambient





Package Outline

SOIC-8, 8 leads



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	1.350	1.750	0.053	0.069
A1	0.100	0.250	0.004	0.010
A2	1.250	1.650	0.049	0.065
b	0.310	0.510	0.012	0.020
c	0.170	0.250	0.007	0.010
D	4.800	5.000	0.189	0.197
e	1.270 (BSC)		0.050 (SBC)	
E	5.800	6.200	0.228	0.244
E1	3.800	4.000	0.150	0.157
L	0.400	1.270	0.016	0.031
θ	0°	8°	0°	8°